

# Modular IPC Roadmap

Modular IPC, ISG, IIoT BU

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Mar, 2025



# Change List

| Page | Affected Product Line               | Description                                                                                                                                                                                                                                                |
|------|-------------------------------------|------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| P.4  | MIC-7000 Series                     | <ul style="list-style-type: none"><li>• Remove MIC-7500/ MIC-760</li><li>• MIC-7700-A EOL (LTB: Sep. 2025, LTS: Mar: 2026)</li><li>• Add MIC-7700-B estimated MP date/ LTB/ LTS schedule</li><li>• Update MIC-780 estimated MP date to July 2025</li></ul> |
| P.5  | MIC-7000 Series Thermal Enhancement | <ul style="list-style-type: none"><li>• Add a page for i-Module of Add a page for MIC-7000 Series Thermal Enhancement Product</li></ul>                                                                                                                    |
| P.7  | i-Module (MIC-780)                  | <ul style="list-style-type: none"><li>• Update MIC-78MG30 estimated MP date to Sep. 2025</li><li>• Update MIC-78M13 estimated MP date to Sep. 2025</li><li>• Add MIC-78G30 in planning</li></ul>                                                           |
| P.8  | Advanced Flex I/O                   | <ul style="list-style-type: none"><li>• 98910770301 EOL (LTB: June. 2025, LTS: Sept. 2025)</li><li>• 98910770320 / 98910770330 / 98910770340 / 98910770350 MP</li><li>• Add 98910770600/ 98910770610/ 98910770700/ 98910770710 in planning</li></ul>       |
| P.9  | MIC-7000 Domain-Focus Product       | <ul style="list-style-type: none"><li>• Add a page for MIC-7000 Domain-Focus Product</li></ul>                                                                                                                                                             |

# Change List

| Page | Affected Product Line             | Description                                                                                                                                                                                                                                                              |
|------|-----------------------------------|--------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| P.11 | AIIS Series                       | <ul style="list-style-type: none"><li>• AIIS-3400/3410 EOL (LTB: Sep. 2025, LTS: Sep. 2026)</li><li>• Add AIIS-3412 and AIIS-1400 in planning</li></ul>                                                                                                                  |
| P.12 | Add-on Card for Machine Vision/FA | <ul style="list-style-type: none"><li>• Add PCE-USB 4/8 -20 version in planning</li></ul>                                                                                                                                                                                |
| P.14 | AIMC Series<br>Micro IPC          | <ul style="list-style-type: none"><li>• Add AIMC-200 and AIMC-300 status (planning)</li><li>• AIMC-3403 EOL (LTB: Sep. 2025, LTS: Sep. 2026)</li><li>• AIMC-3202 EOL (LTB: Sep. 2025, LTS: Sep. 2026)</li><li>• Update AIMC-200 estimated MP date to Nov. 2025</li></ul> |

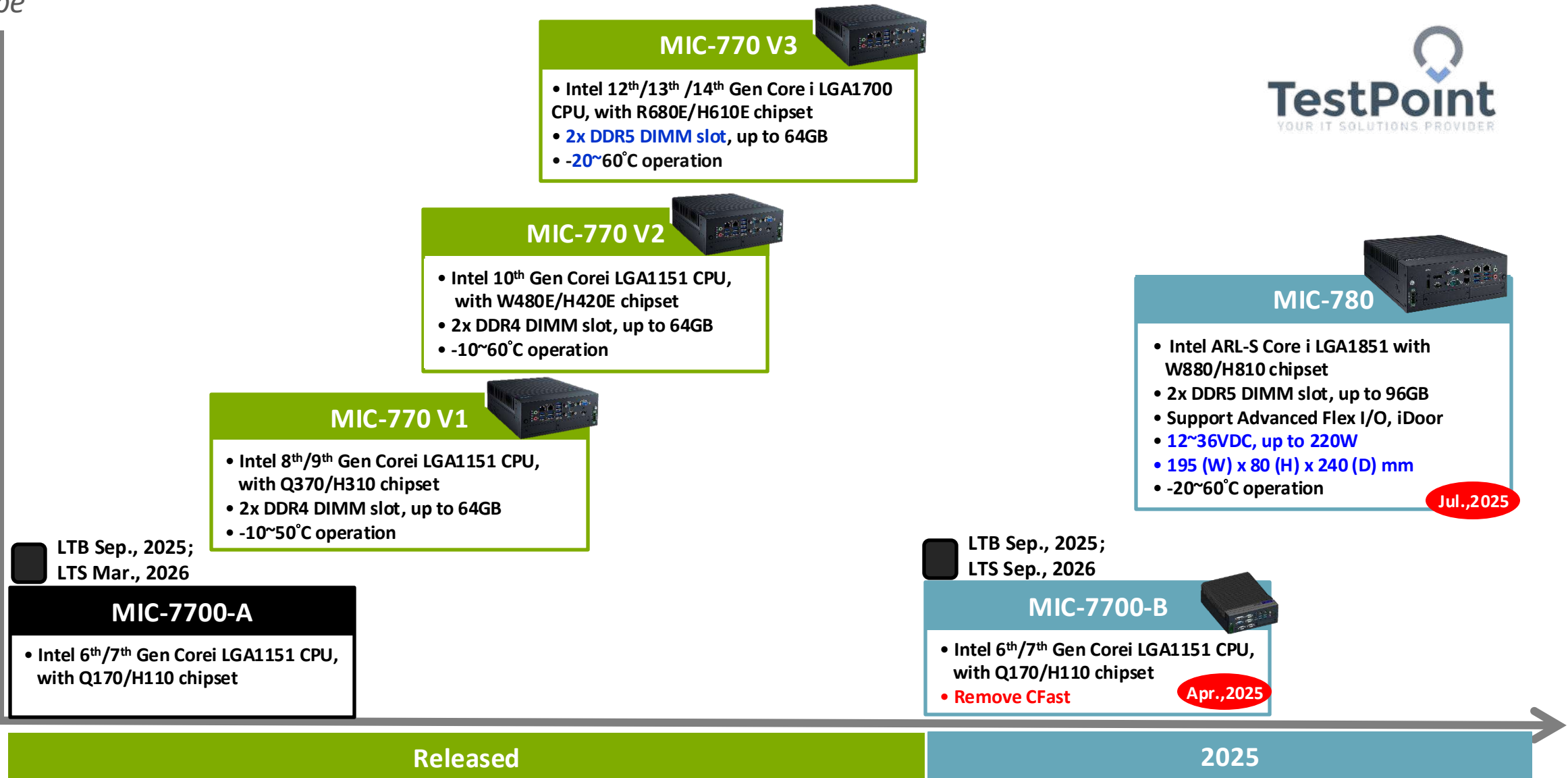
# MIC-7000 Series Product Roadmap

Available Developing Planning EOL



CPU Type

Core i



Time to Market

# MIC-7000 Series Thermal Enhancement Product Roadmap

Available Developing Planning EOL

Thermal solution



Fan Kit solution

## MIC-7000 fan kit



- Support MIC-7700, MIC-770 V1/V2/V3
- 65W CPU, Fan Kit surface Temp. around 61.2 °C

## MIC-780 Fan-SKU



- Support MIC-780
- 65W CPU, Fan Kit surface Temp. around 62°C (TBD)
- MIC-780W-F0A1, MIC-780H-F0A1

Aug., 2025

Extreme SKU

## MIC-770 V3 E-SKU



- Intel 12<sup>th</sup>/13<sup>th</sup> /14<sup>th</sup> Gen Core i LGA1700 CPU, with R680E/H610E chipset
- Support i-Module, Advanced Flex I/O, iDoor
- 35W CPU, up to -20~50°C w/o air flow
- 65W CPU, up to -20~35°C w/o air flow
- MIC-770V3W-E0A1, MIC-770V3H-E0A1

## MIC-780 E-SKU



- Intel ARL-S Core i LGA1851 with W880/H810 chipset
- 2x DDR5 DIMM slot, up to 96GB
- Support i-module, Advanced Flex I/O, iDoor
- 12~36VDC, up to 220W
- 35W CPU, up to -20~50°C w/o air flow (TBD)
- 65W CPU, up to -20~35°C w/o air flow (TBD)
- MIC-780W-E0A1, MIC-780H-E0A1

1H, 2026

Released

2025

2026

Time to Market

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# MIC-75 Series i-Module Product Roadmap

Available Developing Planning EOL



Positioning

Featured



**MIC-75S00**

- 2x Removable 2.5" SSD/HDD
- Compatible with MIC-7 and i-Module



**MIC-75GF10**

- 1xPClex16 with MXM T1000/RTX-3000 GPU
- 1xPClex4 for IO card
- 2x 2.5" HDD Bay

**MIC-75G20-C**

- 1xPClex16/ 1xPClex4
- Fit RTX-4080, 350W GPU
- Triple deck GPU
- 2x 2.5" HDD Bay



MP

**MIC-75G30-C**

- 2xPClex16/ 1xPClex4
- Fit dual RTX-4080
- 3.5 deck GPU, 3x fans models supported
- 2x 2.5" HDD Bay



MP

4-Slot

**MIC-75M13**

- 1xPClex16/3xPCI

**MIC-75M40**

- 1xPClex8/3xPClex4

**MIC-75S20**

- 1xPClex16/1xPClex4
- 2x Hot-swap 2.5" HDD

**MIC-75M40-01**

- 1xPClex8/2xPClex4
- Support GPU card, up to 70W
- For MIC-770 V3



1~2-Slot

**MIC-75M10**

- 1xPClex16



**MIC-75M11**

- 1xPClex16/1xPCI

**MIC-75M20-01**

- 2xPClex8

**MIC-75M20-C**

- 1xPClex16
- 1xPClex4
- Fit GTX-1650Ti (Double deck)

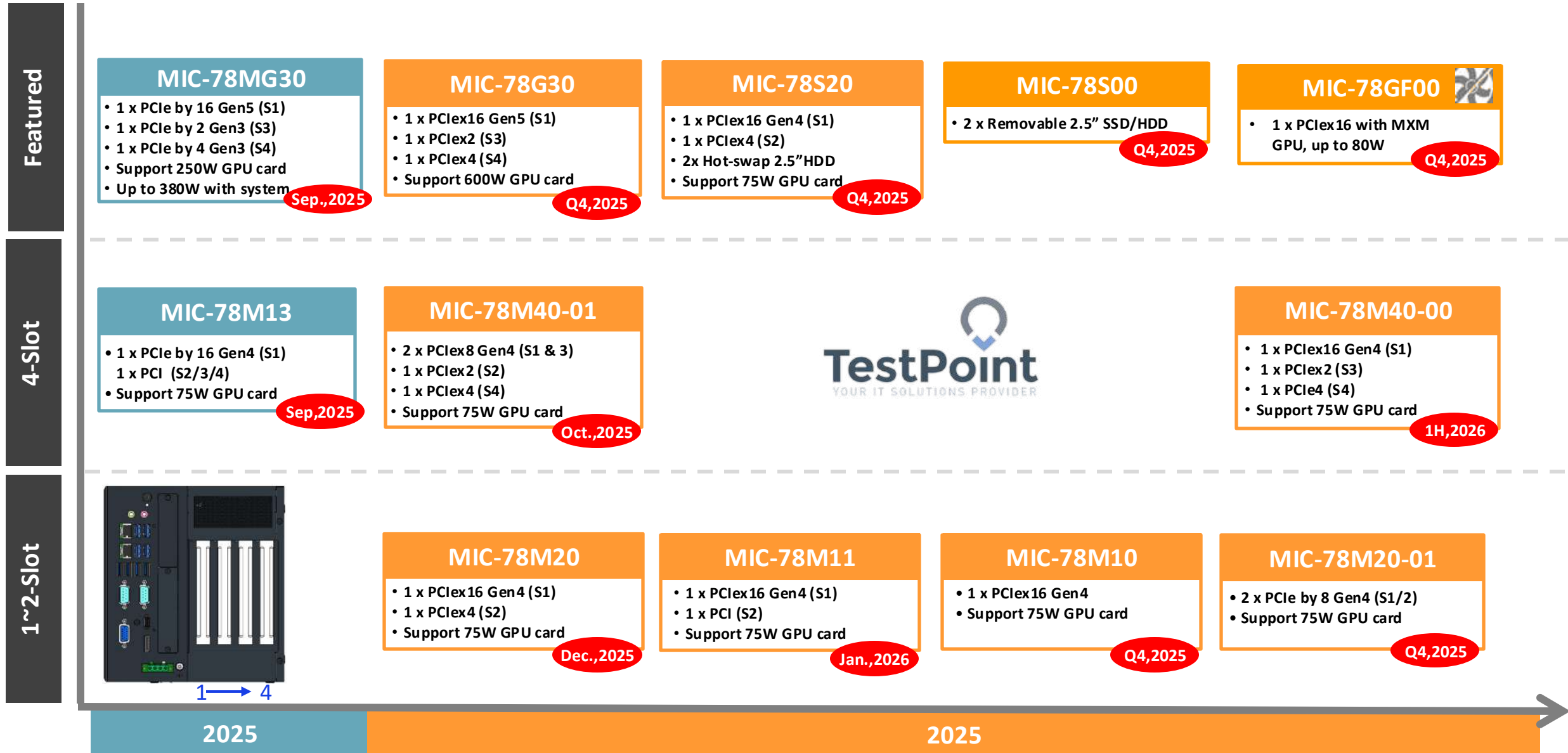


Released

# MIC-78 i-Module Product Roadmap

Available Developing Planning

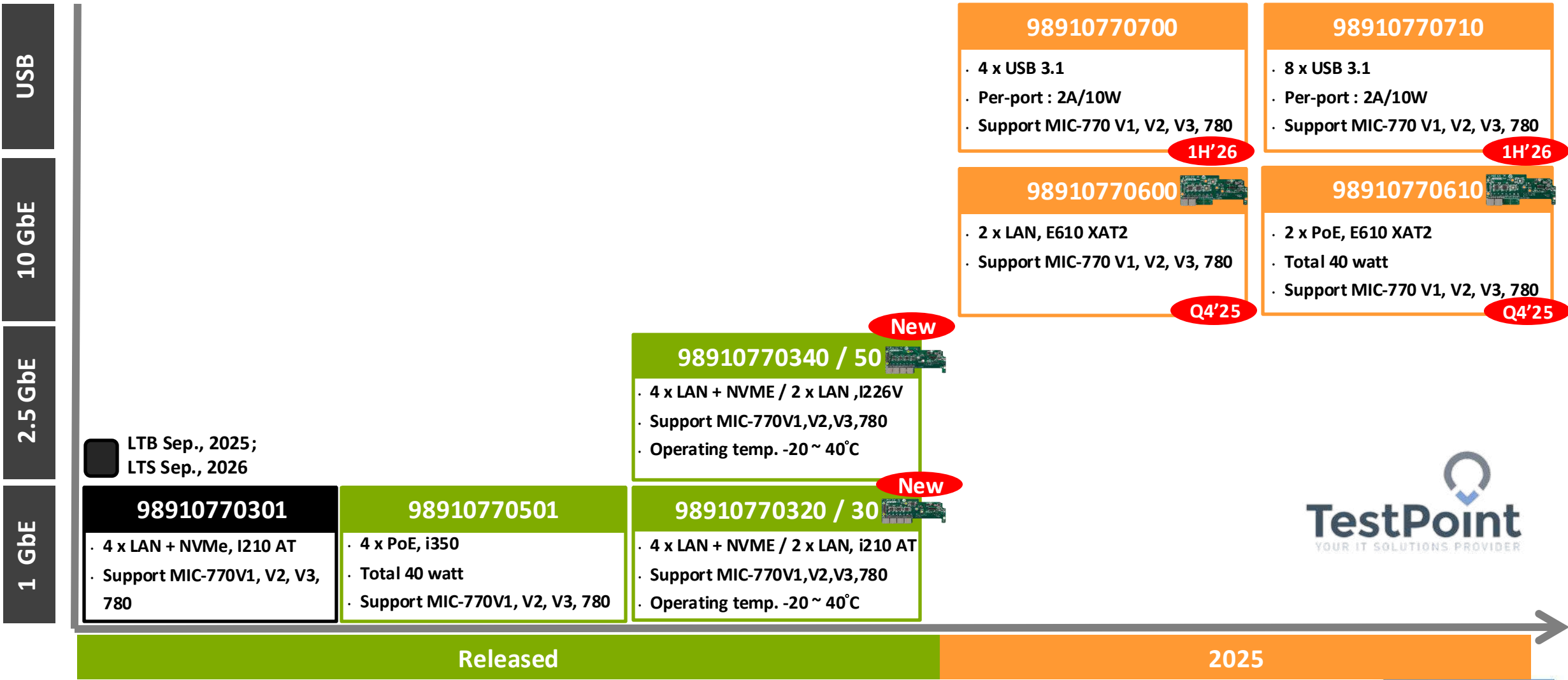
Positioning



# Advanced Flex I/O

Available Developing Planning EOL

Feature



# MIC-7000 Domain-Focus Product Roadmap

Available Developing Planning EOL

Vertical

TBD

AMR

## MIC-760



- Compact Fanless AMR Controller
- Intel 12<sup>th</sup>/13<sup>th</sup> Gen Core i LGA1700 35W CPU, with H610E chipset
- 2x DDR5 DIMM slot, up to 96GB
- Isolated CANBus/DIO/COM
- 12~36VDC, up to 220W
- 160 (W) x 55 (H) x 200 (D) mm
- -20~60°C operation
- ROS2 BSP (Iron Irwini, LTS) /Hardware API
- Ubuntu 22.04 PREEMPT\_RT

Dec., 2025

2025

Time to Market

  
**TestPoint**  
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# AIIS Series Machine Vision IPC



# AIIS Product Roadmap

Positioning

Performance Fan based

Entry



■ LTB Sep., 2025;  
■ LTS Sep., 2026

## AIIS-3410P/U AIIS-3400P/U

- Change to B Version, MOSFET EOL
- 4-CH PoE / 4-CH USB3.0
- Intel Core i7 LGA1151 (Skylake)
- 1 Expansion slot: PCIe x8 or PCI





### AIIS-3411P/U

- Intel 10<sup>th</sup> Gen Core i CPU w/ H420E
- 2 x DDR4 SODIMM RAM Max 64GB
- 4ch independent control IC for GbE PoE/USB 3.0
- Optional AIIS-1882 for 32ch isolated DIO, 4-ch PWM lighting control





### AIIS-3412P/U

Q2,2026

- Intel 12<sup>th</sup> Gen Core i CPU w/ R680E
- 2 x DDR5 SODIMM RAM Max 64GB
- 2 port 10GbE PoE/4 port USB3.2
- Optional AIIS-1882 for 32ch isolated DIO, 4-ch PWM lighting control





### AIIS-1400P/U

Q2,2026

- Intel® Alder Lake-N N97
- 1 x DDR5 SODIMM RAM Max 16GB
- 2-4 port 10GbE PoE/4 port USB3.2 (TBD)
- DIN Rail / Wall Mount option installation



Released

Released

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# Add-on Card for Machine Vision/FA Product Roadmap

Positioning

Available Developing Planning EOL

USB Interface

## PCE-USB 4/8

- PCIe 4 GEN2 interface
- Renesas USB 3.0 controller
- 4-CH : Independent USB3.0 IC per each port
- 8-CH: Two ports share one USB3.0 IC
- Maximum current/watt per-port : 1.5A/7.5W
- Dimension (WxH) : 117 x 111mm



## PCE-USB 4/8-20

- PCIe 4 GEN2 interface
- **USB 3.2 controller, 10G / port**
- 4-CH : Independent USB3.2 IC per each port
- 8-CH: Two ports share one USB3.2 IC
- Maximum current/watt per-port : 1.5A/7.5W
- Dimension (WxH) : 117 x 111mm



Q4, 2025

RJ45 Interface

## PCE-GIGE 2/4-02

- PCIe 4 GEN2 interface
- Intel i210 (10/100/1000MB/s)
- SKU : 2 LAN/ 4 LAN
- Dimension (WxH) : 117 x 111mm
- Memory mapping for compatibility enhancement



Released

2025

  
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# AIMC Series Micro IPC



# AIMC Series Product Roadmap

■ Available
 ■ Developing
 ■ Planning
 ■ EOL



4 slot  
Compact-size

■ LTB Sep., 2025;  
■ LTS Sep., 2026

## AIMC-3403

- Intel SKL-S CPUs / H110
- DDR4 2133 Max 32GB
- 10 COM, 8 USB, 2LAN
- 1 x PCIe x 16, 2 x PCIe x 1, 1 x PCI
- 250W AC power



## AIMC-3405

- Intel Comet Lake CPUs / H420E
- DDR4 2933/2666/2400 MHz  
UDIMM, MAX 64GB
- 6 COM, 8 USB, 2LAN
- 1 x PCIe x 16, 1 x PCIe x 4
- 250W AC power



2 slot+  
Compact-size

■ LTB Sep., 2025;  
■ LTS Sep., 2026

## AIMC-3202

- Intel KBL-S/SKL-S CPUs / H110
- DDR4 2133 Max 32GB
- 2COM, 3USB, 2LAN
- 1 PCIe x16+ 1 x4 or 1 PCIe x16 +1 PCI
- 250W AC Power



Fanless  
System

## AIMC-2000J

- Change to B version, RTL LAN EOL
- Intel BayTrail J1900 SoC
- DDR3 Max 16GB
- 6COM, 8USB, 2LAN, 1 miniPCle
- 12V DC IN



## AIMC-200

Nov., 2025

- Intel® Processor N97/i3-N305 Edge Computer
- 1 x DDR4, Max 16GB
- 2 x LAN, 6 x COM, 6 x USB, 2 x HDMI
- 1 x M.2 B Key support iDoor, 1 x M.2 E Key
- 12V DC IN



## AIMC-300

Q3, 2025

- Intel® Tiger Lake i7/i5/i3 Processor
- 2 x DDR4, Max 32GB
- 4 x LAN, 4 x COM, 4 x USB, 1 x DP, 1 x HDMI
- 1 x M.2 B Key, 1 x M.2 M key, 2 x miniPCle
- 10-36V DC IN



Released

2025

2025

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